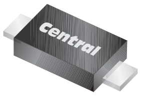
Material Composition Specification

SOD-123FL Case

Central Semiconductor Corp.



Device average mass . . . . **8.34 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.47%	0.039	Si	7440-21-3	0.43%	0.036	4,318
				Au	7440-57-5	0.04%	0.003	360
bond wire	gold	0.01%	0.001	Au	7440-57-5	0.01%	0.001	120
leadframe	Cu alloy w/ silver plating	45.6%	3.802	Cu	7440-50-8	44.38%	3.7	443,789
				Fe	7439-89-6	1.08%	0.09	10,795
				Ag	7440-22-4	0.14%	0.012	1,439
encapsulation	EMC	53.12%	4.429	SiO_2	14808-60-7	38.38%	3.2	383,817
				epoxy resin	29690-82-2	6.6%	0.55	65,969
				phenol resin	9003-35-4	6.6%	0.55	65,969
				Sb_2O_3	1309-64-4	0.42%	0.035	4,198
				Br	7726-95-6	1.13%	0.094	11,275
plating	tin alloy	0.8%	0.066	Sn	7440-31-5	0.78%	0.065	7,796
				Bi	7440-69-9	0.02%	0.0013	156

R1 (3-June 2011)